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RX240128A-YHW

SPECIFICATION

CUSTOMER:

APPROVED BY

PCB VERSION

DATE

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
Release DATE:			



Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2012/04/28		First issue
A	2013/04/19		Modify Supply
			Current 120 MAX
			Modify Display
			Command
			Correct VLCD
			Correct pin
			Description.
В	2014/11/26		Remove IC
			information
С	2016/01/15		Add Pull Tape
D	2016/02/25		Modify Precautions in
			use of LCD Modules
			& Static electricity
			test



Contents

- 1. General Specification
- 2.Module Classification Information
- 3.Interface Pin Function
- 4. Contour Drawing
- **5.Optical Characteristics**
- 6. Absolute Maximum Ratings
- 7. Electrical Characteristics
- 8.Backlight Information
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of LCD Modules
- 12. Material List of Components for RoHs
- 13.Recommendable Storage



1.General Specification

The Features is described as follow:

- Module dimension: 98.7 x 67.7 x 9.5 mm
- View area: 92.0 x 53.0 mm
- Active area: 83.975 x 44.775 mm
- Number of dots: 240 x 128
- Dot size: 0.325 x0.325 mm
- Dot pitch: 0.35 x 0.35 mm
- LCD type: STN Positive, Yellow Green Transflective
- Duty: 1/128
- View direction: 6 o'clock
- Backlight Type: LED White
- IC: UC1608



2.Module Classification Information

<u>R</u>	<u>X</u>	<u>240128</u>	<u>A</u>	_	<u>Y</u>	<u>H</u>	W
1	2	3	4	_	5	6	\bigcirc

Item		C	escriptio	on					
1	R : Raystar Optronics Inc.								
2	Diaplay	C: Character Type,		T:TAB Type	\rightarrow				
2	Display	G: Graphic Type		X:COG Type					
3	Display Font :	240 * 128 dot			(
4	Serials code :	r							
		P→TN Positive, Gray		V→FSTN Ne	egative, Blue				
		N→TN Negative,			egative, Black				
		L→VA Negative		D→FSTN N	egative (Double film)				
		$H \rightarrow HTN$ Positive, Gray		F→FSTN Pc	ositive				
5	LCD	I→HTN Negative, Black		K→FSC Neg					
		U→HTN Negative, Blue		S→FSC Pos					
		B→STN Negative, Blue			gative, Black				
		G→STN Positive, Gray		C→CSTN Negative, Black					
		Y→STN Positive, Yellow		A→ASTN Negative, Black					
		A : Reflective, N.T, 6:00		K: Transflective, W.T,12:00					
	Polarizer	D: Reflective, N.T, 12:0		1 : Transflective, U.T,6:00					
	Туре,	G: Reflective, W. T, 6:00			ctive, U.T.12:00				
	Temperature	J: Reflective, W. T, 12:0			ssive, N.T,6:00				
6	range,	0 : Reflective, U. T, 6:00			ssive, N.T,12:00				
		3 : Reflective, U. T, 12:0			sive, W. T, 6:00				
	View	B: Transflective, N.T,6:0			sive, W.T,12:00				
	direction	E : Transflective, N.T.12			sive, U. T, 6:00				
		H : Transflective, W.T,6:			sive, U.T,12:00				
		$N \rightarrow$ Without backlight		D, White	$H \rightarrow LED$, High light White				
		$P \rightarrow EL, Blue$, Amber	$S \rightarrow LED$, Full color				
		T→EL, Green	R→LED		$J \rightarrow DIP LED, Blue$				
7	Daukiiuiii), Orange	$K \rightarrow DIP LED, White$				
	Y	$M \rightarrow EL$, Yellow Green	B→LED	Ť	$E \rightarrow DIP LED, Yellow$				
		$F \rightarrow CCFL$, White		, Dual color	$L \rightarrow DIP LED, Amber$				
		Y→LED, Yellow Green	C→LED	, Full color	$I \rightarrow DIP LED, Red$				
		G→LED, Green							

3.Interface Pin Function

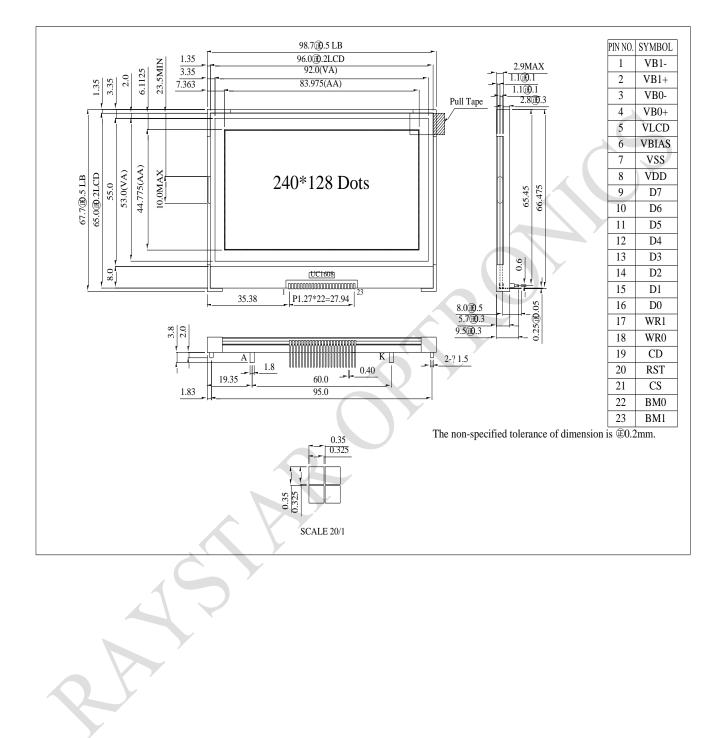
Pin No.	Symbol	Туре			Descript	ion				
1	VB1-			LCD Bias Voltages. These are the voltage source to						
2	VB1+		provide SEG driving currents. These voltages are generated internally. Connect capacitors of CBX between							
3	VB0-		VBX+ and VBX							
5	V D0-	PWR	The res	istance of the	ese four trac	es directly a	ffects the			
4	VB0+			8 8	n of the resu	J				
4	VDU+		Minimizo quality in		esistance is	critical in ach	nieving high			
5	VLCD	PWR		0	ipply. Conne	ect these pins	s together.			
					voltage to g		•			
							ine VLCD by			
6	VBIAS	1	external	variable res	sistors. Interr	hal resistor n	etwork has			
Ū		•			nplify externa	•				
				•••	connect a sr VSS to redu		capacitor			
7	VSS	PWR	Ground							
8	VDD	PWR		Voltage for lo	oaic					
9	D7				r both serial	and parallel	host			
10	D6		interface	es.						
			In serial	modes, con	nect D[0] to	SCK, D[3] to	o SDA,			
11	D5			BM=1x (Parallel)	BM=0x (Parallel)	BM=01	BM=00 (S8/S8uc)			
12	D4		D0	DO	D0/D4	(S9) SCK	SCK			
13	D3	I/O	D1 D2	D1 D2	D1/D5 D2/D6		-			
14	D2		D3 D4	D3 D4	D3/D7	SDA	SDA			
15	D1		D5	D5	-	-	-			
	~		D6 D7	D6 D6 – S9 S8/S8uc D7 D7 0 1 1						
16	D0		Connect unused pins to VDD or VSS.							
17	WR1	Ι		WR[1:0] controls the read/write operation of the host interface. See Host Interface section for more detail.						



18	WR0		In parallel mode, WR[1:0] meaning depends on whether the interface is in the 6800 mode or the 8080 mode. In serial interface modes, these two pins are not used, connect them to VSS.					
19	CD	I	operation	. In S9 m	a or Display data for read/write ode, CD pin is not used. Connect CD to d. "L": Control data "H": Display data			
20	RST	I	When RST="L", all control registers are re-initialized by their default states. Since UC1608x has built-in Power-ON-Reset and Software Reset command, RST pin is not required for proper chip operation. When RST is not used, connect the pin to VDD.					
21	CS	I	•		hip is selected when CS="H". When the d, D[7:0] will be high impedance.			
22	BMO				erface bus mode is determined by by the following relationship: <u>Mode</u> 6800/8-bit 8080/8-bit 6800/4-bit			
23	BM1		01 0X 0800/4-bit 00 0X 8080/4-bit 01 10 3-wire SPI w/ 9-bit token (S9: conventional) 00 10 4-wire SPI w/ 8-bit token (S8: conventional) 00 11 3- or 4-wire SPI w/ 8-bit token (S8uc: Ultra-Compact)					



4.Contour Drawing



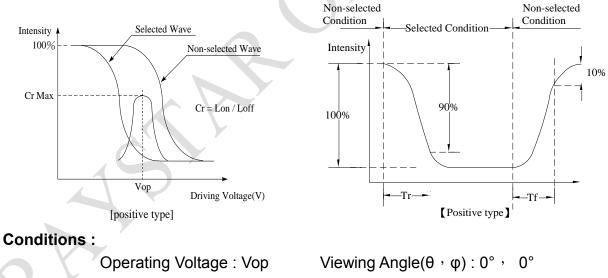


5.Optical Characteristics

ltem	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0		20	ψ= 180°
) (iour Angele	θ	CR≧2	0		40	ψ= 0°
View Angle	θ	θ CR≧2		_	30	ψ= 90°
	θ	CR≧2	0	1	30	ψ= 270°
Contrast Ratio	CR	_	-	3	_	_
	T rise	-		200	300	ms
Response Time	T fall			250	350	ms

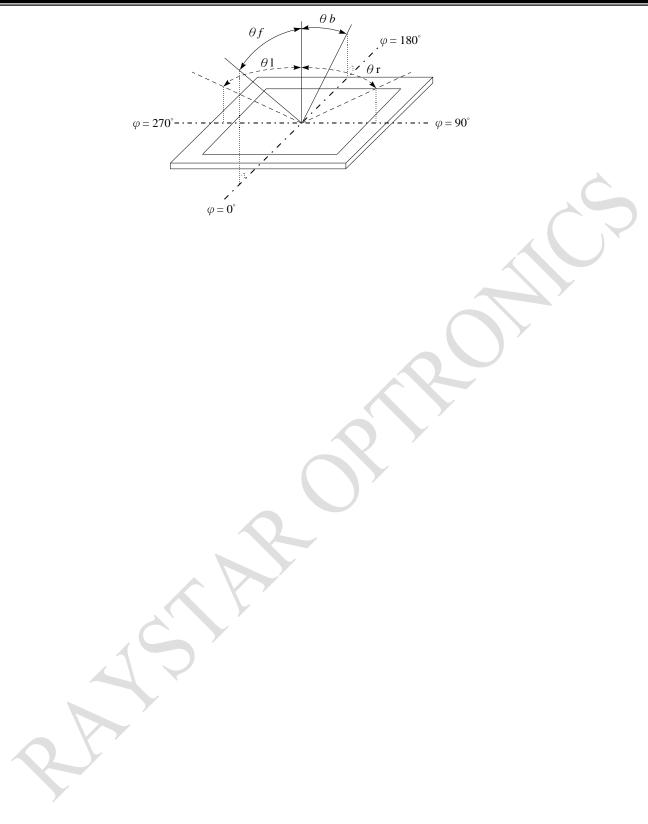
Definition of Operation Voltage (Vop)

Definition of Response Time (Tr , Tf)



Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR≥2)





6.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Мах	Unit
Operating Temperature	Тор	-20		+70	°C
Storage Temperature	T _{ST}	-30	_	+80	°C
Logic supply voltage	V _{DD}	-0.3	_	+4.0	V
LCD Generator supply voltage	V _{DD} 2	-0.3	-	+4.0	V
LCD Generated voltage	VLCD	-0.3	-	+17.0	V



7.Electrical Characteristics

ltem	Symbol	Condition	Min	Тур	Мах	Unit
Supply Voltage For		_	2.7	2.8~3.3	3.6	V
Logic	V _{DD} -V _{SS}		2.1	2.0~3.3	3.0	V
		Ta=-20°C		_		v
Supply Voltage For LCM	VLCD	Ta=25°C	15.2	15.5	15.8	V
		Ta=70°C	_		-	V
Input High Volt.	VIH	—	0.8 VDD		_	V
Input Low Volt.	VIL	-	-)	_	0.2 V _{DD}	V
Output High Volt.	Vон		0.8 V _{DD}	_	_	V
Output Low Volt.	Vol				0.2 V _{DD}	V
Supply Current(No						
include	ldd	V _{DD} =3.0V	—	1.1	—	mA
LED Backlight)						

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

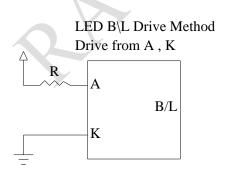
8.Backlight Information

Specification

PARAMETER	SYMBOL	MIN	ТҮР	МАХ	UNIT	TEST CONDITION
Supply Current	ILED	86.4	96	120	mA	V=3.5V
Supply Voltage	v	3.3	3.5	3.7	v	
Reverse Voltage	VR	_	_	5	v	-
Luminance (Without LCD)	IV	400	500	_	CD/M2	ILED=96mA
Meye Length	X	0.28	0.3	0.32		ILED=96mA
Wave Length	Y	0.28	0.3	0.32		
LED Life Time					~	ILED≦96mA
(For Reference	_	-	50K)-	Hr.	25°C,50-60%RH,
only)						(Note 1)
Color	White					

Note: The LED of B/L is drive by current only ; driving voltage is only for reference To make driving current in safety area (waste current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.





9.Reliability

	Environmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times	

Content of Reliability Test (Wide temperature, -20°C~70°C)

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



10.Inspection specification

NO	Item			Criterion		AQL				
		1.1 Missing vert	ical, horizo	ontal segment, seg	ment contrast					
		defect.	defect.							
		1.2 Missing cha	racter, dot	t or icon.						
	Electrical	1.3 Display malf	function.							
01	Testing	1.4 No function	or no displ	ay.	C	0.65				
	resting	1.5 Current cons	sumption e	exceeds product s	pecifications.	\square				
		1.6 LCD viewing	g angle def	fect.						
		1.7 Mixed produ	ict types.							
		1.8 Contrast def	fect.							
	Black or white	2.1 White and b	lack spots	on display ≤ 0.25	mm, no more than					
02	spots on LCD	three white c	or black sp	ots present.	Y	2.5				
	(display only)	2.2 Densely spa	aced: No m	nore than two spot	s or lines within	2.0				
	(display only)	3mm			1					
		3.1 Round type	: As follow	ring drawing						
		Φ=(x + y) /	2	SIZE	Acceptable Q TY					
				Ф≦0.10	Accept no dense					
				0.10<Φ≦0.20	2					
				0.20<Φ≦0.25	1	2.5				
				0.25<Ф	0	2.0				
	LCD black	x	1							
	spots, white		Y .							
03	spots,	•	TY							
	contamination		32.05							
	(non-display)	3.2 Line type : (As followin	ig drawing)						
		2.00	Length	Width	Acceptable Q TY					
1				W≦0.02	Accept no dense					
		→ L ←	L≦3.0	$0.02 \! < \! W \! \le \! 0.03$	2	2.5				
	5	200	L≦2.5	$0.03 \! < \! W \! \le \! 0.05$	2					
				0.05 <w< td=""><td>As round type</td><td></td></w<>	As round type					

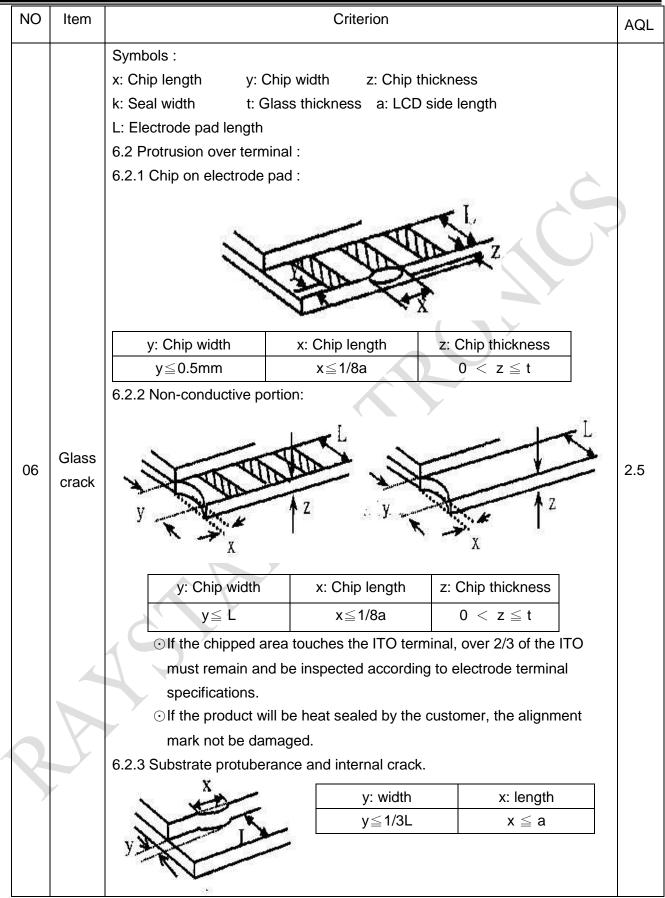


04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size Φ $\Phi \leq 0.20$ $0.20 < \Phi \leq 0.50$ $0.50 < \Phi \leq 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3 3	2.5
----	----------------------	-------------------------------------------------------------------------------------------------------------------------------	-------------------------------------------------------------------------------------------------------	-------------------------------------------------------------	-----



NO	Item	Criterion				
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination				
			Glass thickness a: LCD	hickness 9 side length		
		6.1 General glass chip 6.1.1 Chip on panel sur	face and crack between	panels:		
		z: Chip thickness	y: Chip width	x: Chip length		
06	Chipped	Z≦1/2t	Not over viewing area	x≦1/8a	2.5	
00	glass	$1/2t < z \leq 2t$	Not exceed 1/3k	x≦1/8a	2.5	
	4	⊙ If there are 2 or more6.1.2 Corner crack:	e chips, x is total length o	f each chip. Y		
	N'	z: Chip thickness	y: Chip width	x: Chip length		
R	J.	Z≦1/2t	Not over viewing area	x≦1/8a		
		$1/2t < z \leq 2t$	Not exceed 1/3k	x≦1/8a		
		\odot If there are 2 or more	chips, x is the total leng	th of each chip.		







NC	ltem	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
		8.1 Illumination source flickers when lit.	0.65
08	Backlight	8.2 Spots or scratched that appear when lit must be judged.	2.5
	elements	Using LCD spot, lines and contamination standards.	
		8.3 Backlight doesn't light or color wrong.	0.65
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5
09	Bezel	stains or other contamination.	0.65
		9.2 Bezel must comply with job specifications.	
		10.1 COB seal may not have pinholes larger than 0.2mm or	
		contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.	
		10.3 The height of the COB should not exceed the height	2.5
		indicated in the assembly diagram.	0.65
		10.4 There may not be more than 2mm of sealant outside the	2.5
		seal area on the PCB. And there should be no more than	2.5
		three places.	
		10.5 No oxidation or contamination PCB terminals.	2.5
10	PCB COB	10.6 Parts on PCB must be the same as on the production	0.65
		characteristic chart. There should be no wrong parts,	0.00
		missing parts or excess parts.	
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	
		screw hold pad, make sure it is smoothed down.	2.5
		10.9 The Scraping testing standard for Copper Coating of PCB	
			2.5
		X	
		'Y' X * Y<=2mm2	
	7	11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections,	2.5
11	Soldering	oxidation or icicle.	
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65



NO	ltem	Criterion	AQL
NO 12	Item General appearance	Criterion 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened.	 2.5 0.65 2.5 2.5 2.5 2.5 2.5
		12.8 Pin type must match type in specification sheet.	0.65 0.65
		12.9 LCD pin loose or missing pins.12.10 Product packaging must the same as specified on	0.65
		packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	

Shr





11.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.



12.Material List of Components for RoHs

1. RAYSTAR Optronics. Inc. hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs	
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	
Above limited value is set up according to RoHS.							

- 2.Process for RoHS requirement : (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow : 250°C,30 seconds Max. ;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C ;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.



13.Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

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Page: 1

	LCM Sample	e Estimate Feedback Sheet
Module Number :		
1 · Panel Specification		
1. Panel Type:	□ Pass	□ NG ,
2. View Direction :	□ Pass	□ NG ,
3. Numbers of Dots :	□ Pass	□ NG ,
4. View Area :	□ Pass	□ NG ,
5. Active Area :	□ Pass	□ NG ,
6.Operating Temperature :	Pass	□ NG ,
7.Storage Temperature :	Pass	□ NG ,
8.Others :		
2 · Mechanical Specification :		
1. PCB Size :	□ Pass	□ NG ,
2.Frame Size :	□ Pass	□ NG ,
3.Materal of Frame :	□ Pass	□ NG ,
4.Connector Position :	□ Pass	□ NG ,
5.Fix Hole Position :	□ Pass	□ NG ,
6.Backlight Position :	□ Pass	□ NG ,
7. Thickness of PCB :	Pass	□ NG ,
8. Height of Frame to PCB :	Pass	□ NG ,
9.Height of Module :	🗆 Pass	□ NG ,
10.Others :	Pass	□ NG ,
3 · <u>Relative Hole Size</u> :		
1.Pitch of Connector :	Pass	□ NG ,
2.Hole size of Connector :	Pass	□ NG ,
3.Mounting Hole size :	□ Pass	□ NG ,
4.Mounting Hole Type :	Pass	□ NG ,
5.Others :	Pass	□ NG ,
4 · Backlight Specification :		
1.B/L Type:	Pass	□ NG ,
2.B/L Color :	□ Pass	□ NG ,
3.B/L Driving Voltage (Referen	nce for LED T	ype) : □ Pass □ NG ,
4.B/L Driving Current :	Pass	□ NG ,
5.Brightness of B/L :	Pass	□ NG ,
6.B/L Solder Method :	Pass	□ NG ,
7.Others :	□ Pass	□ NG ,

>> Go to page 2 <<



Page: 2

Module Number :					
5 · Electronic Characteristics of Module :					
1.Input Voltage :	□ Pass	□ NG ,			
2.Supply Current :	□ Pass	□ NG ,			
3.Driving Voltage for LCD :	□ Pass	□ NG ,			
4.Contrast for LCD :	□ Pass	□ NG ,			
5.B/L Driving Method :	□ Pass	□ NG ,			
6.Negative Voltage Output :	Pass	□ NG ,			
7.Interface Function :	Pass	□ NG ,			
8.LCD Uniformity :	□ Pass	□ NG ,			
9.ESD test :	□ Pass	🗆 NG ,			
10.Others :	□ Pass	□ NG ,			

6 ∖ <u>Summary</u> :

Sales signature :	
Customer Signature :	

D	ate	:	/ /	/
				_